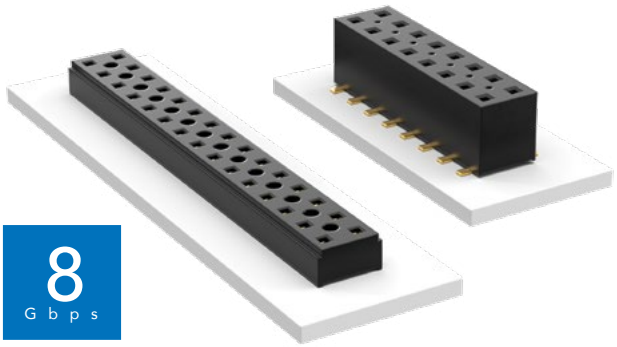
COST-EFFECTIVE & DUAL WIPE SOCKETS

8 Gbps

(2.00 mm) .0787" PITCH • TLE/CLT SERIES



TLE
Mates:
TMMH, TMM, MTMM, MMT, TW, LTMM, ZLTMM, TCMD, TSH

CLT
Mates:
TMM, TMMH, MTMM, MMT, TW, TSH

SPECIFICATIONS

TLE
Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au over 50 µ" (1.27 µm) Ni
Current Rating (TLE/TMMH):
3.2 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(2.08 mm) .082" to
(4.37 mm) .172" with
(0.38 mm) .015" wipe,
pass-through, or
(3.35 mm) .132" min
for bottom entry

CLT
Same as TLE except:
Plating:
Sn or Au over 50 µ" (1.27 µm) Ni
Current Rating (TMMH/CLT):
4.1 A per pin
(2 pins powered)
Insertion Depth:
Top Entry=
(1.40 mm) .055" minimum
Bottom Entry=
(2.57 mm) .101" minimum
(add board thickness for
correct post OAL)
Max Cycles:
100 with 10 µ" (0.25 µm) Au

PROCESSING

TLE
Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-26)
(0.15 mm) .006" max (27-50)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)

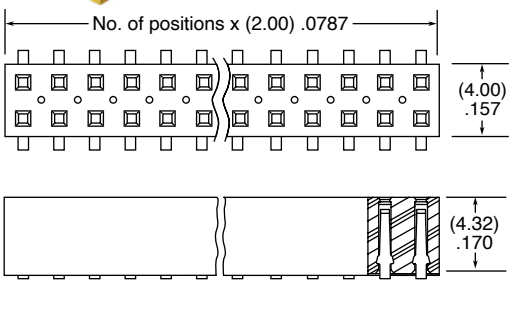
CLT
Same as TLE except:
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-25)
(0.15 mm) .006" max (26-34)*
(0.20 mm) .008" max (35-50)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)

Note:
Some lengths, styles and options are non-standard, non-returnable.

TLE – 1 – NO. PINS PER ROW – 01 – PLATING OPTION – DV – OPTIONS

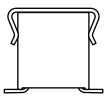
TIGER™ BEAM CONTACT

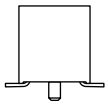
NO. PINS PER ROW: 02 thru 50

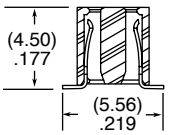


PLATING OPTION

–G
= 10 µ" (0.25 µm) Gold


–P Option


–A Option



OPTIONS

–A
= Alignment Pin
(3 positions minimum)

–K
= (5.00 mm) .197" DIA
Polyimide Film Pick & Place Pad
(3 positions minimum)

–P
= Metal Pick & Place Pad
(4 positions minimum)

–TR
= Tape & Reel Packaging
(2-37 positions only)

-FR
= Full Reel Tape & Reel
(must order maximum quantity per reel; contact Samtec for quantity breaks)
(2-37 positions only)

CLT – 1 – NO. PINS PER ROW – LEAD STYLE – PLATING OPTION – D – OTHER OPTIONS

TIGER™ CLAW CONTACT

NO. PINS PER ROW: 02 thru 50

LEAD STYLE

–01
= Through-hole

–02
= Surface Mount

–03
= Through-hole

ALSO AVAILABLE
MOQ Required
Other Platings

PLATING OPTION

–F
= Gold flash on contact, Matte Tin on tail

–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

–G
= 10 µ" (0.25 µm) Gold on contact, Gold flash on tail

OTHER OPTIONS

All options require Style –02

–BE
= Bottom Entry
(Required for bottom entry applications)

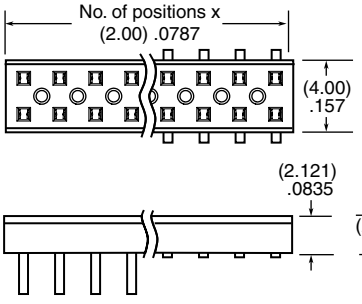
–A
= Alignment Pin
(3 positions minimum)
Metal or plastic at Samtec's discretion

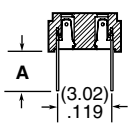
–K
= (5.00 mm) .197" DIA
Polyimide Film
Pick & Place Pad
(04 thru 50 only)

–P
= Pick & Place Pad
(4 positions minimum)
(Not always necessary for auto placement.)

–TR
= Tape & Reel
(36 positions max)

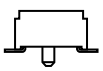
–FR
= Full Reel Tape & Reel
(must order maximum quantity per reel; contact Samtec for quantity breaks)
(36 positions max)

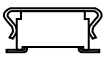




–01 or –03

LEAD STYLE	A
–01	(2.16) .085
–03	(2.95) .116


–A Option


–P Option

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.